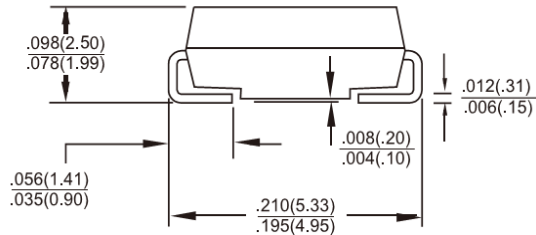
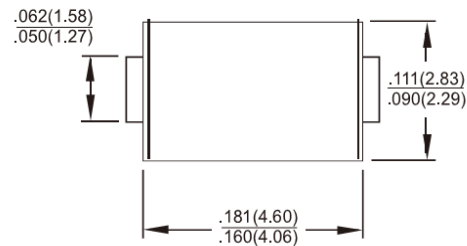


**SMA/DO-214AC**

**RoHS COMPLIANCE**

**Features**

- ✧ UL Recognized File # E-326243
- ✧ Glass passivated junction chip.
- ✧ For surface mounted application
- ✧ Low forward voltage drop
- ✧ Low profile package
- ✧ Built-in stain relief, ideal for automatic placement
- ✧ Fast switching for high efficiency
- ✧ High temperature soldering: 260°C/10 seconds at terminals
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✧ Green compound with suffix "G" on packing code & prefix "G" on datecode


**Dimensions in inches and (millimeters)**
**Marking Diagram**


- HS2XA = Specific Device Code
- G = Green Compound
- Y = Year
- M = Work Month

**Mechanical Data**

- ✧ Case: Molded plastic
- ✧ Terminal: Pure tin plated, lead free
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 12mm tape per EIA STD RS-481
- ✧ Weight: 0.064 grams

**Maximum Ratings and Electrical Characteristics**

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	HS 2AA	HS 2BA	HS 2DA	HS 2FA	HS 2GA	HS 2JA	HS 2KA	HS 2MA	Unit	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	300	400	600	800	1000	V	
Maximum RMS Voltage	$V_{RMS}$	35	70	140	210	280	420	560	700	V	
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	300	400	600	800	1000	V	
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.5								A	
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	50								A	
Maximum Instantaneous Forward Voltage (Note 1) @ 1.5A	$V_F$	1.0			1.3		1.7			V	
Maximum Reverse Current @ Rated VR $T_A=25\text{ }^\circ\text{C}$ $T_A=125\text{ }^\circ\text{C}$	$I_R$	5 100								$\mu\text{A}$	
Maximum Reverse Recovery Time (Note 2)	$T_{rr}$	50					75				nS
Typical Junction Capacitance (Note 3)	$C_j$	50					30				pF
Typical Thermal Resistance (Note 4)	$R_{\theta JA}$	80								$^\circ\text{C/W}$	
Operating Temperature Range	$T_J$	- 55 to + 150								$^\circ\text{C}$	
Storage Temperature Range	$T_{STG}$	- 55 to + 150								$^\circ\text{C}$	

Note 1: Pulse Test with PW=300 usec, 1% Duty Cycle

 Note 2: Reverse Recovery Test Conditions:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$ 

Note 3: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

Note 4: PCB Mount on 5mm x 5mm Copper Pad Area

## RATINGS AND CHARACTERISTIC CURVES (HS2AA THRU HS2MA)

FIG.1 FORWARD CURRENT DERATING CURVE

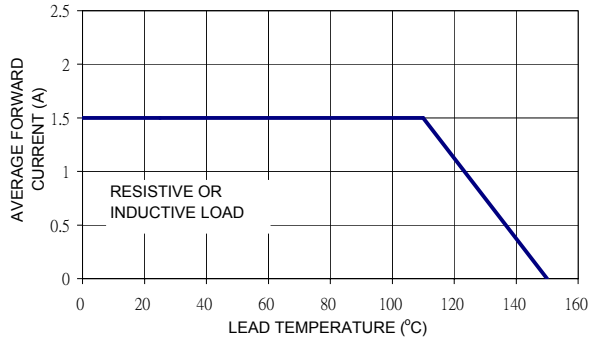


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

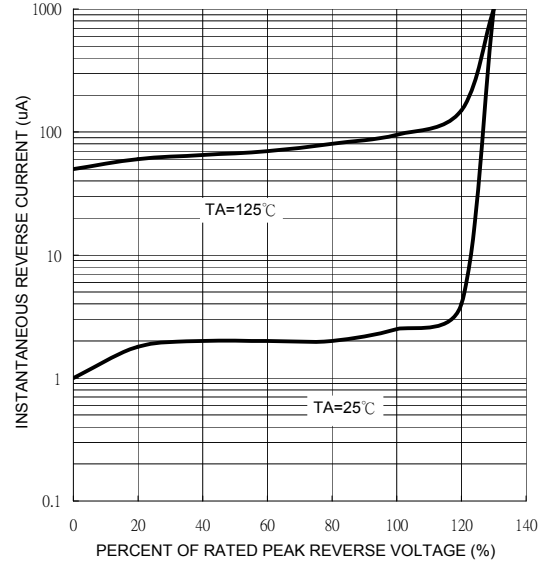


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

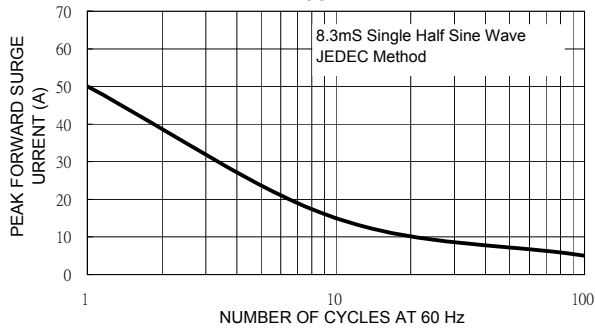


FIG. 5 TYPICAL FORWARD CHARACTERISTICS

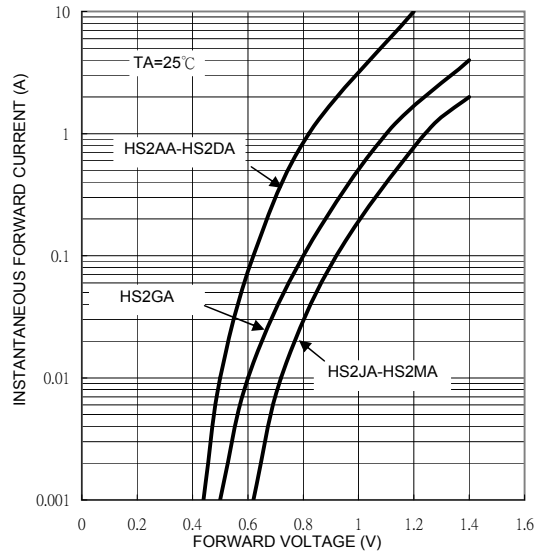


FIG. 4 TYPICAL JUNCTION CAPACITANCE

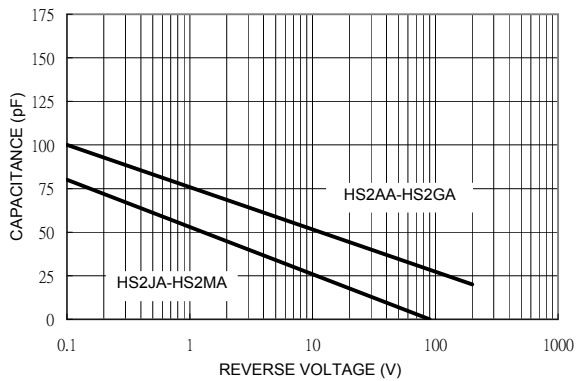


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

